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TITLE: SEMICONDUCTOR DEVICE
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ABSTRACT:

PURPOSE: To enhance reliability by interposing an elastic wiring board between a bump electrode and a mounting board and supporting the elastic wiring board at positions corresponding to the rows of bump electrodes thereby suppressing concentration of stress, due to micro displacement caused by temperature cycle, to the bump electrodes.

CONSTITUTION: A mounting board 13 and a cap 14 secured through an adhesive layer 15 to the periphery of the mounting board 13 constitute a cavity 17 for encapsulating a semiconductor pellet 1. The semiconductor pellet 1 is secured through an adhesive 16 to the cap 14 thus electrically connecting the semiconductor pellet 1 with the mounting board 13 through bump

electrodes 3.

In such semiconductor device, an elastic wiring board 5 is interposed between

the bump electrodes 3 and the mounting board 13 with the elastic wiring board 5

being supported at positions corresponding to the rows of the bump electrodes

3. The elastic wiring board 5 is composed of polyimide resin or epoxy resin, for example.

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